



Material Content Data Sheet



Sales Product Name				ESD233-B1-W0201 E6327		Issued		19. January 2018	
MA#				MA001643352					
Package				SG-WLL-2-1		Weight*		0.07 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.063	94.57	94.57	945660	945660	
pad	inorganic material	silicon	7440-21-3	0.000	0.00		15		
	non noble metal	copper	7440-50-8	0.000	0.00		30		
	inorganic material	phosphorus	7723-14-0	0.000	0.09		857		
	noble metal	gold	7440-57-5	0.000	0.09		902		
	non noble metal	aluminium	7429-90-5	0.000	0.34		3442		
	noble metal	palladium	7440-05-3	0.000	0.56		5622		
	non noble metal	nickel	7440-02-0	0.003	4.13	5.21	41278	52146	
passivation	inorganic material	SiO2	60676-86-0	0.000	0.07		691		
	inorganic material	siliciumnitride	12033-89-5	0.000	0.15	0.22	1503	2194	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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